In an integrated circuit (IC) structure the positioning of through silicon vias (TSVs) in terms of the physical layout of circuitry is described. An IC structure can include a plurality of first circuit elements (D1 G1 & S; 702 706 710 & 714; or 702 706 704 & 708); a plurality of second circuit elements (D2 G2 & S; 704 708 712 & 716; or 710 714 712 & 716); a plurality of first TSVs (410 & 510; 605 620; or 720 734); and a plurality of second TSVs (415 & 505; 625 640; or 736 750). The first and second circuit elements and the first and second TSVs together comprise a circuit block configuration. The circuit block configuration is symmetric with respect to at least one axis of symmetry. At least one of the first TSVs is a dummy TSV without which the circuit block configuration would not be symmetric.

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